The 13th International Conference on Position Sensitive Detectors PSD13 St. Catherine's College, Oxford, September 3-8, 2023

Novel photon detectors

Peter KrižanUniversity of Ljubljana and J. Stefan Institute

Introduction: why?

Photon detectors are at the heart of most experiments in particle physics. Moreover, they are also finding application in other scientific fields (chemistry and biology) and are ubiquitous in society in general.

New environments where we need to detect light (in particular low light levels) \rightarrow need advances in existing technology and transformative, novel ideas to meet the demanding requirements.

Two main lines of R&D to be pursued have been identified by the ECFA Detector R&D Roadmap:

- Enhance timing resolution and spectral range of photon detectors.
- Develop photosensors for extreme environments.

This talk: photosensors will be discussed in this spirit; also: the main emphasis will be on low light level detection.

Contents

Introduction: why and what kind of photosensor?

- Vacuum-based photodetectors
- Solid state low light level photosensors
- Gas-based photodetectors
- Summary and outlook

Vacuum-based photodetectors

Generic steps:

- •Photon \rightarrow photoelectron conversion
- • Photoelectron collection in themultiplication system
- \bullet Mutiplication (dynodes, microchannel plates, high E field $+$ Si)
- \bullet Signal collection

Multianode photomultiplier tubes (PMTs)

Pioneered in the HERA-B RICH, later used in the COMPASS, CLASS12 and GlueX RICH detectors

Recent use in the upgraded LHCb RICH detectors; planned for CBM RICH

Excellent performace (excellent single photon detection efficiency, very low noise, low cross-talk), best choice for large areas with no B field

Micro Channel Plate PMT (MCP-PMT)

Multiplication step: a continuous dynode – a micro-channel

Micro Channel Plate PMT (MCP-PMT)

Sept. 4, 2023 **PSD13** PSD13 PSD13 PSD13 Peter Križan, Ljubljana

MCP PMT ageing

MCP PMTs: photo-cathode degradation due to ion feedback, main concern in high intensity experiments

ALD (atomic layer deposition) coating of MCP $pores \rightarrow \sim 100x$ photo-cathode lifetime increase

- • Hamamatsu 1-inch YH0205 (>20 C/cm²) [K. Inami, 2021]
- • No QE degradation for Photonis MCP-PMT (R2D2) to >34 C/cm²
- • Little QE degradation in LAPPD 8-inch up to 5.6 C/cm² [V. A. Chirayath, CPAD2021]

400 nm PHOTONIS MCP-PMTs

10000

15000

20000

5000

hotek A3191220

Photek A2200606 - PHOT. 9002192 PHOT. 9002193

35000

000 2000 3000 4000 5000 600

integrated anode charge [mC/cm²

30000

integrated anode charge [mC/cm²

25000

MCP-PMT: single photon pulse height and timing

Typical single photon timing distribution with a narrow main peak ($\sigma \sim 40$ ps) and contributions from photoelectron elastic (flat distribution) and inelastic backscattering.

Photoelectron back-scattering produces ^a rather long tail in timing distribution and position resolution.

Photoelectron backscattering reduces collection efficiency and gain, and contributes to cross-talk in multi-anode **PMT_s**

Gain in a single channel saturates at high gains due to space charge effect [→] peaking distribution for single photoelectrons

S.Korpar@PD07

Photoelectron in uniform electric field

Photoelectrons travel from photocathode to the electron multiplier (uniform electric field $\frac{U}{l}$, initial energy $E_0 \ll$ Ue_0 :

• photoelectron range

$$
d_0 \approx 2l \sqrt{\frac{E_0}{Ue_0}} sin(\alpha)
$$

• and maximal travel time (sideway start)

$$
t_0 \approx l \sqrt{\frac{2m_e}{U e_0}}
$$

 • time difference between downward and sideways initial direction

$$
\Delta t \approx t_0 \sqrt{\frac{E_0}{U e_0}}
$$

Example ($U = 200 V$, $\text{E}_0 = 1 eV$, $l = 6 mm$)

photoelectron:

- max range $d_0 \approx 0.8\ mm$
- p.e. transit time $t_0 \approx 1.4 \; ns$
- Δt $\approx 100~\rm ps$

backscattering:

• max range
$$
d_1 = 2l = 12
$$
 mm

• max delay $t_1 = 2.8 \text{ ns}$

Backscattering delay and range (maximum for elastic scattering):

• maximum range vs. angle

 $d_1=2$ lsin(2 β

maximum range for backscattered photoelectron is twice the photocathode – first electrode distance

• maximum delay vs. angle $t_1 = 2 t_0 sin(\beta$

maximum delay is twice the photoelectron travel time

• time of arrival of elestically scattered photoelectrons: flat distribution up to max $t_1=2t_0$

S.Korpar@PD07

LAPPD (large area picosecond photodetector) Gen II

Characteristics (Incom):

- borosilicate back plate with interior resistive ground plane anode -5 mm thick
- capacitively coupled readout electrode
- MCPs with 20 μ m pores at 20 μ m pitch
- two parallel spacers (active fraction \approx 97 %)
- gain $\approx 5 \cdot 10^6$ @ ROP (825 V/MCP, 100 V on photocathode)
- peak QE $\approx 25\%$
- size 230 mm x 220 mm x 22 mm (243 mm X 274 mm X 25.2 mm with mounting case)
- Dark Count rate @ ROP: \sim 70 kHz/cm2 with $8x10^5$ gain

MCP PMT timing

Tails understood (eleastic and inelastic scattering of photoelectrons off the MCP), can be significantly reduced by:

• decreased photocathode-MCP distance and

•increased voltage difference

- prompt signal \sim 70%
- short delay \sim 20%
- \cdot ~ 10% uniform distribution

LAPPD – timing distribution

S. Korpar et al., to be submitted to NIMA

LAPPD – timing vs PC-MCP1 voltage

Time‐walk corrected TDCs for different PC‐MCP1 voltages

Time resolution vs PC‐MCP1 voltage

MCP PMT readout: capacitive coupling vs. internal anodes

Secondary electrons spread out when traveling from the MCP-out electrode to the anode and can hit more than one anode \rightarrow Charge sharing Can be used to improve spatial resolution.

Fraction of the charge detected by the right pad as a function of red laser spot position

oupinig (Spieaus over iarger area*) -* auvantage or not. depends on the usage coupling (spreads over larger area) - advantage or not: depends on the usage Capacitive coupling vs. internal anodes: signal spread comparison for two MCP PMTs with the same pad size, same range: charge sharing is more effective for capacitive

Possible Future of Electron Multiplication

H. van der Graaf et al., NIM A847 (2017) 148Tynodes $(\rightarrow$ Time Photon Counter) **Transmission Reflection** Transmission mode dynode \rightarrow tynode Fabrication of tynodes (MgO ALD, diamond) \heartsuit Trimary electron using MEMS technology Photon Support "Anode" is a CMOS chip (e.g., TimePix) Substrate Very promising properties Diamond Tynode dynode Very compact; high B-field tolerance; very fast Very low DCR; very good 2D spatial resolution Detecting chip Amplified signal

MCP-PMT with CMOS anode

Conceptual design for 4D detection of single photons

Hybrid concept: MCP-PMT where the pixelated anode is an ASIC (CMOS) embedded inside the vacuum Prototype with Timepix4 ASIC as anode (array of 23k pixels)

Envisaged performance

<100 ps time resolution and 5-10 μm spatial resolution Rate capability of >100 MHz/cm² (<2.5 Ghits/s @ 7 cm² area)

Low gain (\sim 10⁴) operation possible \rightarrow x100 lifetime increase

 40 mm

M. Fiorini, RICH2022

Hybrid photodetectors (HPD, HAPD)

Photo-electron acceleration in a static electric field (8kV to 25 kV)

Photo-electron detection with

- •Segmented PIN diode (HPD)
- •Avalanche photo diode (HAPD)
- •Silicon photomultiplier (VSiPMT)

Employed on a large scale:

- •HPD: RICH1+RICH2 of LHCb (Run 1+2), CMS HCAL
- •HAPD: Aerogel RICH detector of Belle II

HAPD: photoelectron backscattering in magnetic field

- around 20% of photoelectrons back-scatter and the maximum range is twice the distance from photocathode to APD ~40mm
- in magnetic field (perp. to the HAPD window) scattered photoelectrons follow magnetic field lines and fall back to the same pad
- photoelectron energy is deposited at the same pad

Sept. 4, 2023 **PSD13** PSD13 PSD13 PSD13 Peter Križan, Ljubljana

Solid state low light level photosensors: Silicon photomultipliers SiPM

An array of APDs operated in Geiger mode – above APD breakdown voltage (microcells or SPADs – single photon avalanche diodes) Detection of photons:

- absorbed photon generates an electron-hole pair
- an avalanche is triggered by the carrier in the high field region \rightarrow signal
- voltage drops below breakdown and avalanche is quenched (passive or active quenching)
- each triggered microcell contributes the same amount of charge to the signal

SiPM: noise

- dark counts are produced by thermal generation of carriers, trap assisted tunnelling or band gap tunnelling
- signal equal to single photon response
- typical rate went from ≈ 1 MHz/mm² to below $100kHz/mm²$ for more recent devices
- roughly halved for every -8 $\rm ^{o}C$
- increases linearly with fluence
- optical cross-talk produced when photons emitted in avalanche initiate signal in neighbouring cell, reduced by screening – trenches
- after-pulses produced by trap-release of carriers or delayed arrival of optically induced carrier in the same cell

A. Gola et al. Sensors 19(2019)308

Sept. 4, 2023 **PSD13** PSD13 PSD13 PSD13 Peter Križan, Ljubljana

SiPM: parameter correlation

Higher overvoltage:

 \triangleright higher field:

- higher avalanche trigger probability \rightarrow higher PDE
- faster signal \rightarrow better timing
- higher gain:
	- better signal to noise (electronic)
	- more optical cross-talk \rightarrow higher ENF, worse timing
	- more after-pulses

Sept. 4, 2023 **PSD13** PSD13 PSD13 PSD13 Peter Križan, Ljubljana

VUV SiPM for cryogenic applications

LAr, LXe applications:

- \triangleright VUV sensitivity required:
	- •128 nm (LAr), 178 nm (LXe)
	- DCR (Hz/mm²) optimization of anti-reflective coating ARC \bullet
	- PDE $\approx 20\ \%$
- \triangleright cryogenic temperatures:
	- •• low DCR $\approx 10 \text{mHz/mm}^2$ dominated by band-band tunnelling, reduced by low-field avalanche region
	- •higher after-pulse rate $\approx 10\%$

 $10⁶$

 $10⁵$

 $10⁴$

 $10³$

 $10²$ $10¹$ $10⁰$ 10^{-1} 10^{-2} 10^{-3}

Cell size = $25 \mu m$

 $\overline{\bullet}$ -SF - 4 V

 \rightarrow SF - 6 V

 $-LF - 4V$

 $-E$ LF - 6 V

50

 Ω

100

150

Temperature (K)

200

250

300

SiPM: single photon timing

Intrinsic TTS of SiPM microcells is extremely fast, $<$ 20 ps for single microcells (SPAD), but timing deteriorates for larger devices. The main contributions: $\frac{2}{3}$ ³⁵⁰
• nonuniformity within microcell (edges)

- nonuniformity within microcell (edges)
- spread between microcells
- overall SiPM capacitance
- λ dependence tails

Comparison of timing properties for single 50μ^m SPAD, 1×1 mm² and 3×3 mm² SiPMs with the same SPAD for microcells:

- timing improves with higher overvoltage larger pulses, at the expense of increased SiPM noise
- best timing resolutions for single cell signals are $\sigma \approx$ 21 ps, 32 ps and 77 ps
- TTS deterioration mainly due to a larger overall capacitance \rightarrow reduced signal slope, $\sigma_t \approx \sigma_{el.} \left(\frac{dU}{dt}\right)^{-1}$

F. Acerbi et al. IEEE TNS 61(2014)2678

SiPM: timing variation

Variation of TTS over the device KETEK PM3375TS-SBO (early design) surface can contribute to overall time spread:

- variation within micro-cell
- variation for different microcells

FBK: Masking of outer regions of micro-cells: Improve signal peaking and mask areas of micro-cell with worse timing

SiPM: timing for multi-cell signals

Optical cross-talk contribution to multi-cell signals spoils timing distribution – does not scale with $\frac{1}{n^{1/2}}$:

- two components for 2-micro-cell signals:
	- double photon events proper scaling
	- single photon with cross-talk, timing somewhere between single and double micro-cell signals and resolution is worse
- ratio between contributions changes with light intensity confirming optical cross-talk origin

• even more components for multi-micro-cell signals

SiPM: timing test with pico-second laser

- •AdvanSiD SiPM ASD-NUV3S-P-40
- •OV=6V, T=-2n5o C

24000

2200

1200 1000

8000 6000 4000

2006

6000

200 1000

• blue laser λ =408nm, \sim 35ps FWHM

Reduction of optical crosstalk

Starting from the NUV-HD technology, FBK and Broadcom jointly developed the NUV-HD-MT technology, adding metal-filled deep trench isolation to strongly suppress optical crosstalk.

Other changes: low electric field variant, layout optimized for timing.

Conceptual drawing of the NUV-HD-MT, with the addition of metal-filled Deep Trench Isolation.

Reduction of optical crosstalk probability in NUV-HD-MT, compared to the "standard" NUV-HD. Measurement without encapsulation resin, i.e. only considering internal crosstalk probability.

A. Gola, RICH2022

Light concentrators

At the device level (lenses, Winston cones):

• reduce active are – reduce DCR (tolerate higher fluences)

• use smaller faster devices

At the micro-cell level (micro-lenses, diffractive lenses, meta lenses):

• compensate for low fill factor – small cells, dSiPM

• concentrate light in cell centre – better timing

Higher concentration – narrower angular acceptance

Imaging light concentrators:

• smaller photon impact angles on the sensor

• can be used with position sensitive arrays

Non-imaging light concentrators:

• larger photon impact angles on the sensor – directly coupled to sensor

SiPM RICH with light concentrators

RICH photon detector module prototype:

- Hamamatsu 64 channel MPPC module S11834-3388DF, 8×8 array of 3×3 mm² SiPMs @ 5 mm pitch
- matching array of quartz light concentrators used
- two 20 mm thick aerogel tiles in focusing configuration ($n = 1.045, 1.055$)
- tested in 5 GeV electron beam at DESY

E. Tahirović et al., NIM A787 (2015) 203

PSD13 PSD13 Peter Križan, Ljubljana

Microlenses

- CMOS SPAD array, 128x128 6μ m diameter $@25 \mu m$ pitch – 5% fill factor
- matching polymer plano-convex micro-lens array

Sept. 4, 2023 **PSD13** PSD13 PSD13 PSD13 Peter Križan, Ljubljana

J.M. Pavia et al. Opt.Exp. 22-4(2014)4202

SiPMs: Radiation damage

Show stopper at fluences above $\sim 10^{11}$ in case single (or few) photon sensitivity is required!

(e.g. expected fluence in the ARICH area of Belle II: 2-20 10^{11} n cm⁻²)

- \rightarrow Use of wave-form sampling readout electronics
- \rightarrow Operating the SiPMs at lower temperature
- \rightarrow Annealing periodically (annealing at elevated temperature is preferred)
- \rightarrow Reducing recovery time to lower cell occupancy
- \rightarrow Radiation resistant SiPMs, other materials?

SiPMs: Radiation damage

Beyond $10^{7} \div 10^{8}$ n_{eq}/cm² little correlation between the DCR before and afterirradiation:

- All technologies seem to "converge" towards similar values
- Independence of bulk damage from contaminants in the SiPM starting material?

DCR (dark count rate) vs fluence

Room temperature annealing (20-25°C) for samples irradiated to $6.4·10^{11}$ 1 MeV n_{eq}/cm² Little effect, knee point at around $1.5 \cdot 10^3$ min (\sim 1 day)

A. Gola, RICH2022

SiPMs: Radiation damage, annealing at elevated temperatures

Dark counts at -30C of a Hamamatsu S13360-1350CS SiPMs: non irradiated (blue) and irradiated up to 10¹¹ (yellow), 10^{12} (green) and 10^{13} (orange) n_{eq}/cm^2

SiPMs: Radiation damage, annealing at elevated temperatures

M. Calvi et al., NIMA 922 (2019) 243-249

DCR at 77 K versus neutron fluence

Blue circles: annealed sample

\rightarrow Annealing helps also at 77 K

New materials

• new higher band gap materials - possibly lower DCR - higher radiation resistance, higher temperature

•(V)UV sensitive

•high dark count rate – dominated by trap assisted tunnelling

4H-SiC:

Gas based photon detectors

Standard photosensitive substance: CsI evaporated on one of the cathodes. Large scale application: \sim 11 m² ALICE RICH

Sept. 4, 2023 **PSD13** PSD13 PSD13 PSD13 Peter Križan, Ljubljana

Gas based photon detectors: recent developments

Instead of MWPC:

•Use chambers with multiple GEM or thick GEM (THGEM) gas amplification stages with transm. or refl. photocathode

•COMPASS RICH: trans. photocathode and 2x THGEM + MicroMegas

Ion damage of the photocathode:

blocking ions – non-aligned GEM holes

 4.5_{mm} 38.5mm 4_{mm} 3 mm 5_{mm}

New developments:

- \bullet Smaller pads
- \bullet Novel photocathode material: nano-diamond layer

S. Dalla Torre, NIM A 970 (2020) 163768

Summary and outlook

Next generation of experiments in particle physics: faster timing, wider spectral range and improved radiation tolerance.

Many new interesting developments underway, in particular in SiPMs and MCP-PMTs – not all of them could be covered in this talk.

A detector R&D collaboration (DRD4) is being set-up to facilitate collaboration in this area of research, expected to start in January 2024.

Rate Capability

A. Lehmann, RICH2022

M. Calvi et al., JINST 15 (2020) P10031 ೯ ೦.೯ ≥ 0.4 diameter 1mm $-diameter 2.4mm$ - without mask R10754 MCP-PM $10⁶$ $10⁷$ 10^{3} $10⁴$ Measured photon rate [kHz]

MaPMT

MaPMT R13742: no gain loss to up 10 MHz/mm²

MCP-PMTs

Gain decreases at high photon rates 2-inch MCP-PMTs: \sim 1 MHz/cm² (with 10 \degree gain) 1-inch Hamamatsu R10754 PMTs: ≥10 MHz/cm² 8-inch LAPPD-64: \sim 100 kHz at 4.6 mm Ø laser spot

Improving the rate capability in MCP-PMTs

- •Lower MCP resistance (ranging at tens of MΩ)
- \bullet Lower capacitance - subdivision of MCP layers into smaller partial areas; the second MCP layer was divided in the previous version of Hamamatsu tubes
- • Low gain operation (for single photon detection) - may be possible with amplifiers included directly in the anode (e.g., monolithic or CMOS designs)

Radiation Tolerance

MaPMT

Recently tested for CBM (H12700 and H8500) Irradiation dose up to **3x1011 n/cm²** and **150 Gy gammas** Few kHz increase of DCR but recovers after few monthsUV glass: 1-2% transmission loss @ 400 nm up to 1 kGy **No negative effects on gain and pulse height spectrum Neutron activation of Kovar metal alloy is a minor effect**

H(A)PD

Radiation tolerance dominated by silicon detector Intensively studied for 144ch HAPD for ARICH @Belle II

Basically **no QE loss at 5x1011 n/cm² Increase of APD leakage current** leads to significantly worse S/N ratio: ~17 before, ~3 after irradiation S/N ratio partly regained by adjusted readout parameters

MCP-PMT

Entrance window: should be similar to other PMTsMCPs: currently no data

C. Pauly et al., NIM A1040 (2022) 167177

SiPM: p-on-n vs. n-on-p

n-on-p: green/red light sensitive:

• electrons drift to Geiger region from substrate and holes from surface side

• higher dark count rate – most of the thermally generated carriers arriving to Geiger region are electrons

p on n - green/blue light sensitive:

• electrons drift to Geiger region from surface and holes from substrate side

• lover dark count rate – most of the thermally generated carriers arriving to the Geiger region are holes

60

A. Gola et al. Sensors 19(2019)308